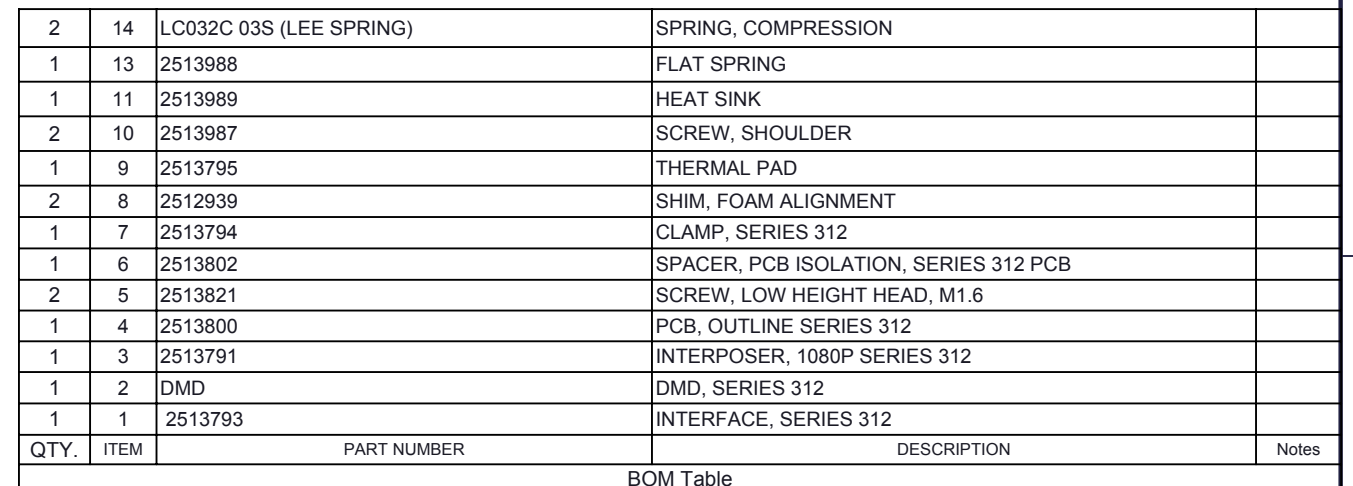
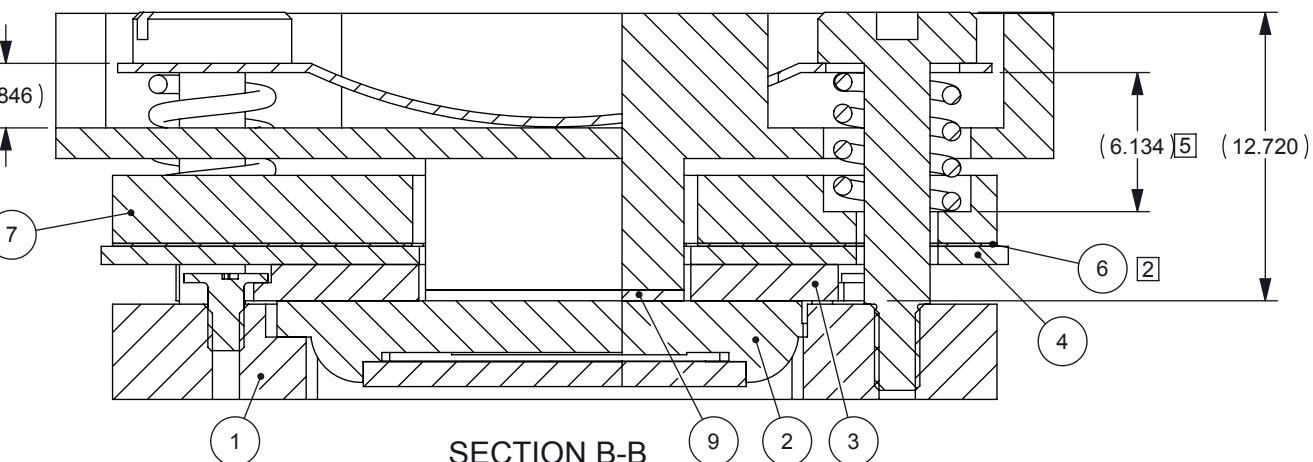


6 CRITICAL GAP FOR FLAT SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. SPECIFIC VALUE WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES

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SSZZ031 January 01, 2013

TEXAS
INSTRUMENTS

DWN
J. MCKINLEY

DATE
2/27/2014

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DRAWING NO
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